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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	ARM7®
Core Size	32-Bit Single-Core
Speed	60MHz
Connectivity	I²C, SPI, SSI, SSP, UART/USART
Peripherals	DMA, PWM, WDT
Number of I/O	72
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/str755fv1t6

regulator and the V_{BACKUP} supply is generated internally by the low power voltage regulator. This scheme has the advantage of requiring only one 5.0V power source.

- **Power Scheme 4: Dual external 5.0V and 1.8V power sources.** In this configuration, the internal voltage regulators are switched off, by forcing the VREG_DIS pin to high level. V_{CORE} is provided externally through the V_{18} and V_{18REG} power pins and V_{BACKUP} through the V_{18_BKP} pin. This scheme is intended to provide 5V I/O capability.

Caution: When powered by 5.0V, the USB peripheral cannot operate.

Low power modes

The STR750F supports 5 low power modes, SLOW, PCG, WFI, STOP and STANDBY.

- SLOW MODE: the system clock speed is reduced. Alternatively, the PLL and the main oscillator can be stopped and the device is driven by a low power clock (f_{RTC}). The clock is either an external 32.768 kHz oscillator or the internal low power RC oscillator.
- PCG MODE (Peripheral Clock Gating MODE): When the peripherals are not used, their APB clocks are gated to optimize the power consumption.
- WFI MODE (Wait For Interrupts): only the CPU clock is stopped, all peripherals continue to work and can wake-up the CPU when IRQs occur.
- STOP MODE: all clocks/peripherals are disabled. It is also possible to disable the oscillators and the Main Voltage Regulator (In this case the V_{CORE} is entirely powered by V_{18_BKP}). This mode is intended to achieve the lowest power consumption with SRAM and registers contents retained. The system can be woken up by any of the external interrupts / wake-up lines or by the RTC timer which can optionally be kept running. The RTC can be clocked either by the 32.768 kHz Crystal or the Low Power RC Oscillator.
  Alternatively, STOP mode gives flexibility to keep the either main oscillator, or the Flash or the Main Voltage Regulator enabled when a fast start after wake-up is preferred (at the cost of some extra power consumption).
- STANDBY MODE: This mode (only available in single supply power schemes) is intended to achieve the lowest power consumption even when the temperature is increasing. The digital power supply (V_{CORE}) is completely removed (no leakage even at high ambient temperature). SRAM and all register contents are lost. Only the RTC remains powered by V_{18_BKP}. The STR750F can be switched back from STANDBY to RUN mode by a trigger event on the WKP_STDBY pin or an alarm timeout on the RTC counter.

Caution: It is important to bear in mind that it is forbidden to remove power from the V_{DD_IO} power supply in any of the Low Power Modes (even in STANDBY MODE).

DMA

The flexible 4-channel general-purpose DMA is able to manage memory to memory, peripheral to memory and memory to peripheral transfers. The DMA controller supports circular buffer management avoiding the generation of interrupts when the controller reaches the end of the buffer.

The DMA can be used with the main peripherals: UART0, SSP0, Motor control PWM timer (PWM), standard timer TIM0 and ADC.

RTC (real-time clock)

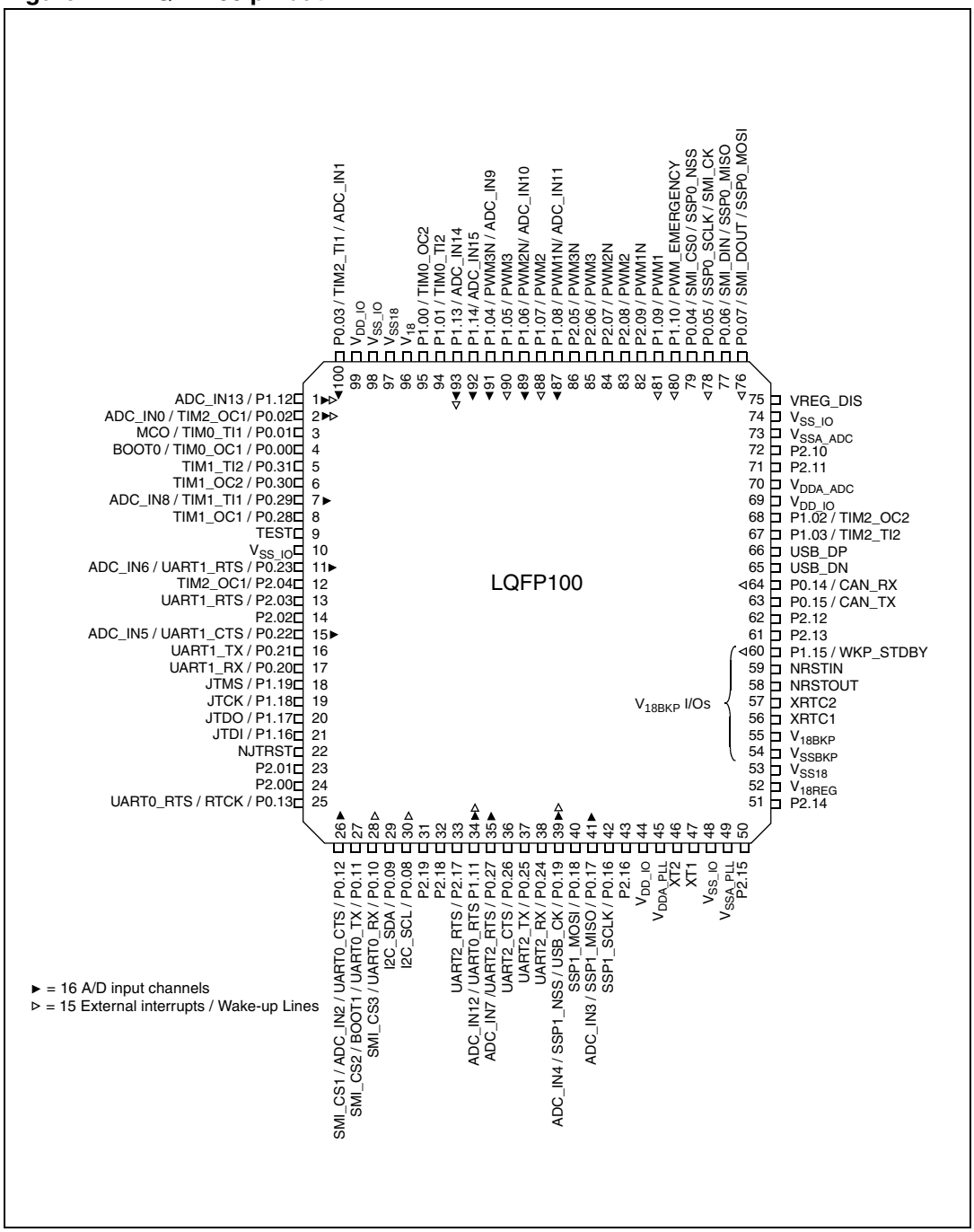
The real-time clock provides a set of continuously running counters which can be used with suitable software to provide a clock calendar function, and provides an alarm interrupt and a

GPIOs (general purpose input/output)

Each of the 72 GPIO pins (38 GPIOs in 64-pin devices) can be configured by software as output (push-pull or open-drain), as input (with or without pull-up or pull-down) or as Peripheral Alternate Function. Port 1.15 is an exception, it can be used as general-purpose input only or wake-up from STANDBY mode (WKP_STDBY). Most of the GPIO pins are shared with digital or analog alternate functions.

4 Pin description

Figure 2. LQFP100 pinout



Port reset state

The reset state of the I/O ports is GPIO input floating. Exceptions are P1[19:16] and P0.13 which are configured as JTAG alternate functions:

- The JTAG inputs (JTDI, JTMS and JTDI) are configured as input floating and are ready to accept JTAG sequences.
- The JTAG output JTDO is configured as floating when idle (no JTAG operation) and is configured in output push-pull only when serial JTAG data must be output.
- The JTAG output RTCK is always configured as output push-pull. It outputs '0' level during the reset phase and then outputs the JTCK input signal resynchronized 3 times by the internal AHB clock.
- The GPIO_PCx registers do not control JTAG AF selection, so the reset values of GPIO_PCx for P1[19:16] and P0. 13 are the same as other ports. Refer to the GPIO section of the STR750 Reference Manual for the register description and reset values.
- P0.11 and P0.00 are sampled by the boot logic after reset, prior to fetching the first word of user code at address 0000 0000h.
- When booting from SMI (and only in this case), the reset state of the following GPIOs is "SMI alternate function output enabled":
  - P0.07 (SMI_DOUT)
  - P0.05 (SMI_CLK)
  - P0.04 (SMI_CS0)
  - P0.06 (SMI_DIN)

  Note that the other SMI pins: SMI_CS1,2,3 (P0.12, P0.11, P0.10) are not affected.

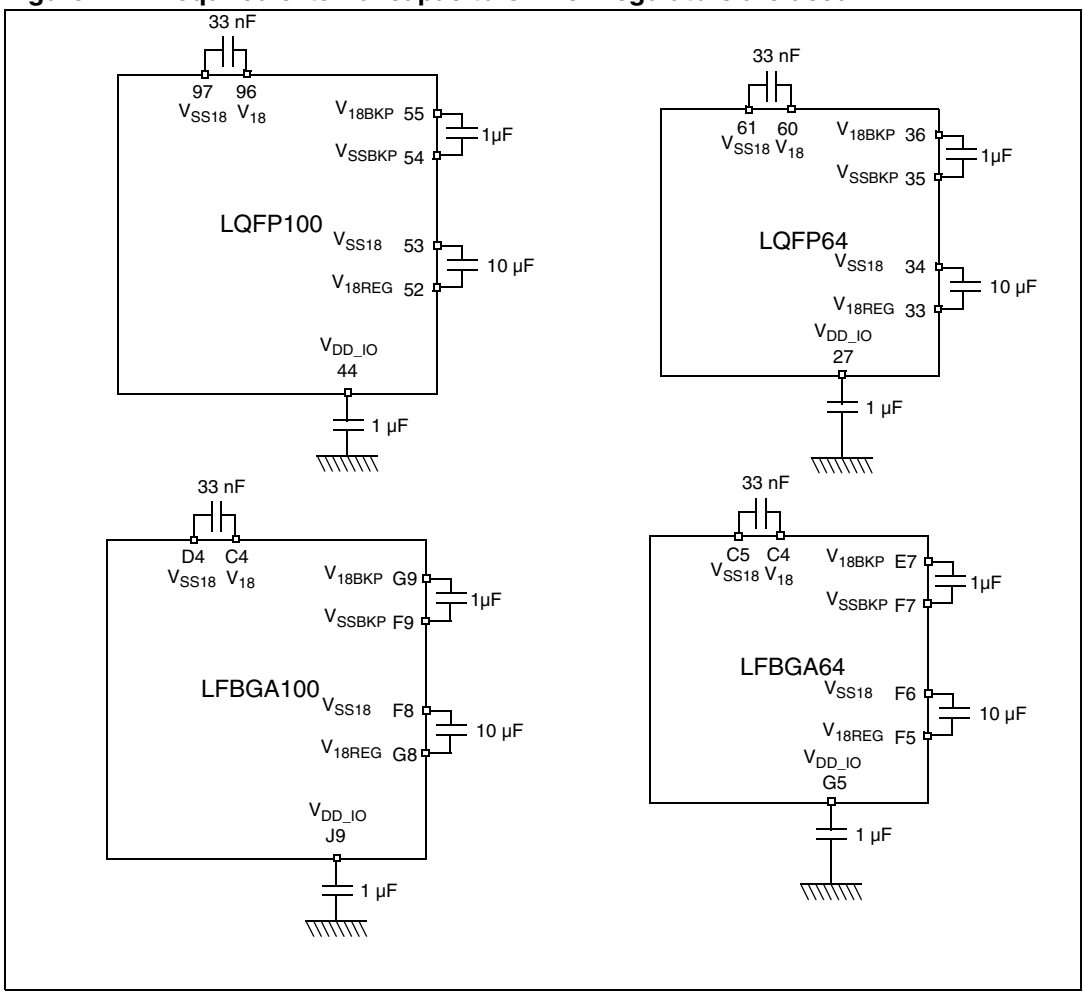
To avoid excess power consumption, unused I/O ports must be tied to ground.

Table 6. STR750F pin description

Pin n°				Pin name	Type	Input				Output			Usable in Standby	Main function (after reset)	Alternate function	
LQFP100[1]	LFBGA100[1]	LQFP64[2]	LFBGA64[2]			Input Level	floating	pu/pd	Ext. int /Wake-up	Capability	OD [3]	PP				
1	B1	1	B1	P1.12 / ADC_IN13	I/O	T_T	**X**	X	EIT12	O8	X	X		**Port 1.12**	ADC: Analog input 13	
2	B2	2	C2	P0.02 / TIM2_OC1 / ADC_IN0	I/O	T_T	**X**	X	EIT0	O8	X	X		**Port 0.02**	TIM2: Output Compare 1[4]	ADC: Analog input 0
3	B3	3	C1	P0.01 / TIM0_TI1 / MCO	I/O	T_T	**X**	X		O8	X	X		**Port 0.01**	TIM0: Input Capture / trigger / external clock 1	Main Clock Output
4	C2	4	C3	P0.00 / TIM0_OC1 / BOOT0	I/O	T_T	**X**	X		O8	X	X		**Port 0.00 / Boot mode selection input 0**	TIM0: Output Compare 1	
5	C1			P0.31 / TIM1_TI2	I/O	T_T	**X**	X		O2	X	X		**Port 0.31**	TIM1: Input Capture / trigger / external clock 2	
6	D2			P0.30 / TIM1_OC2	I/O	T_T	**X**	X		O2	X	X		**Port 0.30**	TIM1: Output Compare 2	

4.2 External components

Figure 4. Required external capacitors when regulators are used



6 Electrical parameters

6.1 Parameter conditions

Unless otherwise specified, all voltages are referred to V_{SS}.

6.1.1 Minimum and maximum values

Unless otherwise specified the minimum and maximum values are guaranteed in the worst conditions of ambient temperature, supply voltage and frequencies by tests in production on 100% of the devices with an ambient temperature at $T_A$max (given by the selected temperature range).

Data based on product characterisation, design simulation and/or technology characteristics are indicated in the table footnotes and are not tested in production. Based on characterization, the minimum and maximum values refer to sample tests and represent the mean value plus or minus three times the standard deviation (mean±3Σ).

6.1.2 Typical values

Unless otherwise specified, typical data are based on T_A=25° C, V_{DD_IO}=3.3 V (for the 3.0 V≤V_{DD_IO}≤3.6 V voltage range) and V_{18}=1.8 V. They are given only as design guidelines and are not tested.

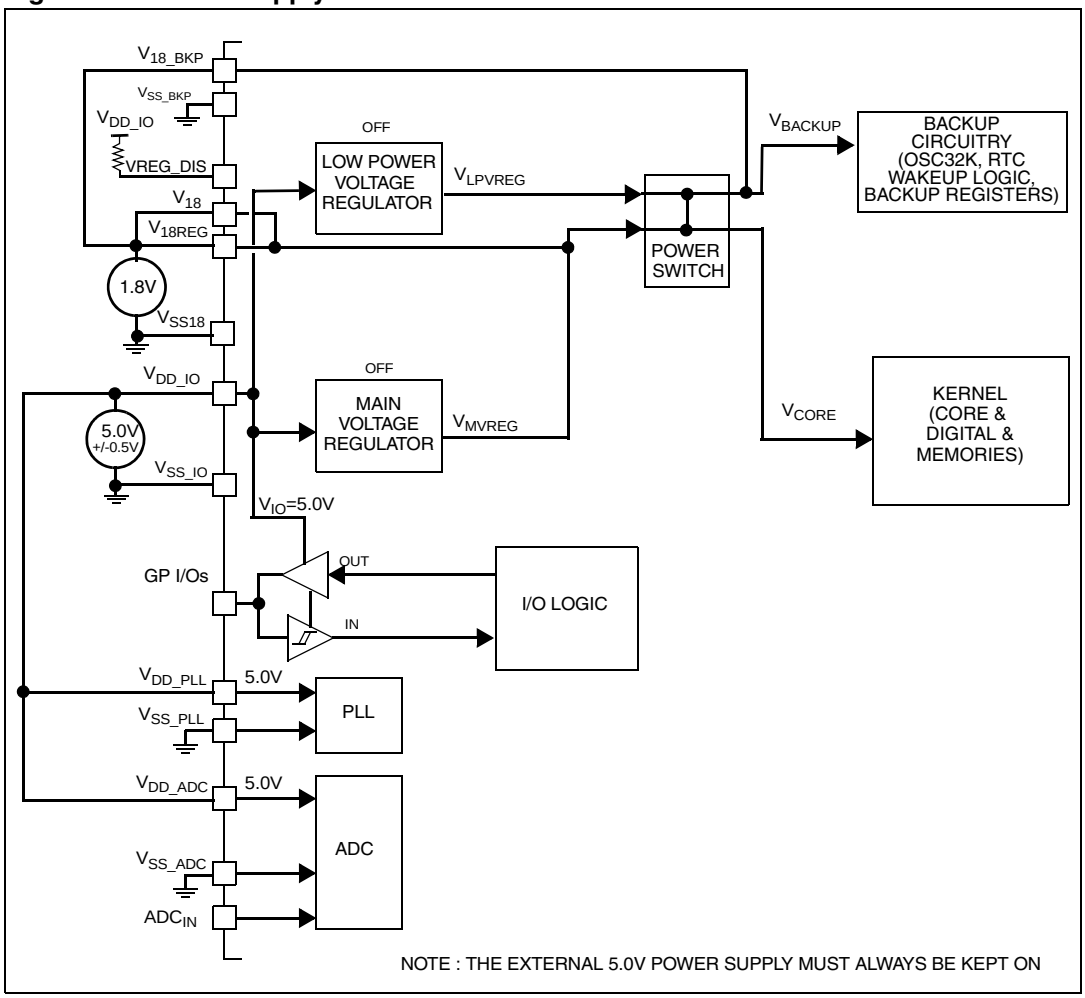
Typical ADC accuracy values are determined by characterization of a batch of samples from a standard diffusion lot over the full temperature range, where 95% of the devices have an error less than or equal to the value indicated (mean±2Σ).

6.1.3 Typical curves

Unless otherwise specified, all typical curves are given only as design guidelines and are not tested.

Power supply scheme 4: Dual external 1.8 V and 5.0 V supply

Figure 11. Power supply scheme 4



6.1.7 I/O characteristics versus the various power schemes (3.3V or 5.0V)

Unless otherwise mentioned, all the I/O characteristics are valid for both

- V_{DD_IO}=3.0 V to 3.6 V with bit EN33=1
- V_{DD_IO}=4.5 V to 5.5 V with bit EN33=0

When V_{DD_IO}=3.0 V to 3.6 V, I/Os are not 5V tolerant.

6.1.8 Current consumption measurements

All the current consumption measurements mentioned below refer to Power scheme 1 and 2 as described in *Figure 12* and *Figure 13*

4/8 MHz crystal / ceramic resonator oscillator (XT1/XT2)

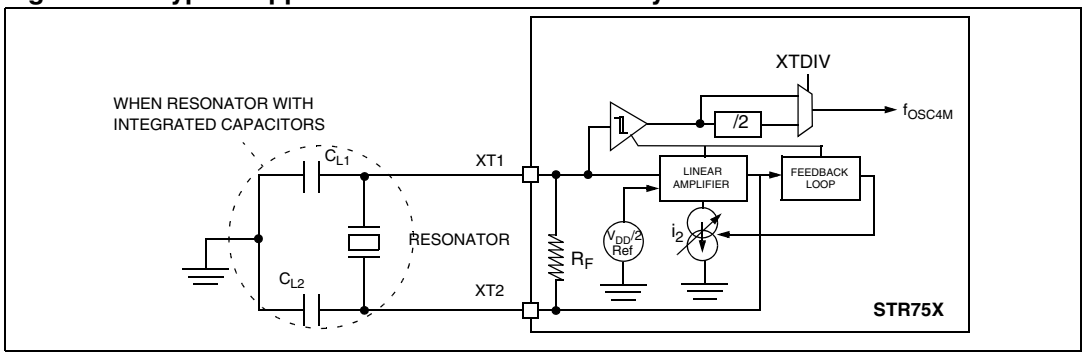
The STR750 system clock or the input of the PLL can be supplied by a OSC4M which is a 4 MHz clock generated from a 4 MHz or 8 MHz crystal or ceramic resonator. If using an 8 MHz oscillator, software set the XTDIV bit to enable a divider by 2 and generate a 4 MHz OSC4M clock. All the information given in this paragraph are based on product characterisation with specified typical external components. In the application, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and start-up stabilization time. Refer to the crystal/ceramic resonator manufacturer for more details (frequency, package, accuracy...).

Table 22. 4/8 MHz crystal / ceramic resonator oscillator (XT1/XT2)(1)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{OSC4M}	Oscillator frequency	4 MHz Crystal/Resonator Oscillator connected on XT1/XT2 XTDIV=0 or 8 MHz Crystal/Resonator Oscillator connected on XT1/XT2 XTDIV=1		4		MHz
R_F	Feedback resistor		200	240	270	kΩ
C_{L1}(2) C_{L2}	Recommended load capacitance versus equivalent serial resistance of the crystal or ceramic resonator (R_S)(3)	R_S=200Ω			60	pF
i_2	XT2 driving current	V_{DD_IO}=3.3 V or 5.0 V		425		µA
$t_{SU(OSC4M)}$(4)	Startup time at V_{DD_IO} power-up			1		ms

1. Resonator characteristics given by the crystal/ceramic resonator manufacturer.
2. For C_{L1} and C_{L2} it is recommended to use high-quality ceramic capacitors in the 5-pF to 25-pF range (typ.) designed for high-frequency applications and selected to match the requirements of the crystal or resonator. C_{L1} and C_{L2}, are usually the same size. The crystal manufacturer typically specifies a load capacitance which is the series combination of C_{L1} and C_{L2}. PCB and MCU pin capacitance must be included when sizing C_{L1} and C_{L2} (10 pF can be used as a rough estimate of the combined pin and board capacitance).
3. The relatively low value of the RF resistor offers a good protection against issues resulting from use in a humid environment, due to the induced leakage and the bias condition change. However, it is recommended to take this point into account if the MCU is used in tough humidity conditions.
4. $t_{SU(OSC4M)}$ is the typical start-up time measured from the moment V_{DD_IO} is powered (with a quick V_{DD_IO} ramp-up from 0 to 3.3V (<50µs) to a stabilized 4MHz oscillation is reached. This value is measured for a standard crystal resonator and it can vary significantly with the crystal/ceramic resonator manufacturer.

Figure 21. Typical application with a 4 or 8 MHz crystal or ceramic resonator



OSC32K crystal / ceramic resonator oscillator

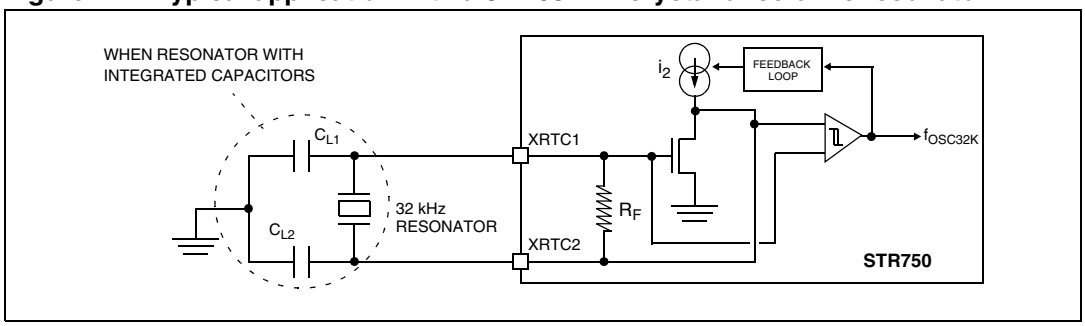
The STR7 RTC clock can be supplied with a 32.768 kHz Crystal/Ceramic resonator oscillator. All the information given in this paragraph are based on product characterisation with specified typical external components. In the application, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and start-up stabilization time. Refer to the crystal/ceramic resonator manufacturer for more details (frequency, package, accuracy...).

Table 23. OSC32K crystal / ceramic resonator oscillator

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{OSC32K}	Oscillator Frequency			32.768		kHz
R_F	Feedback resistor	V_{DD_IO}=3.3 V or 5.0 V	270	310	370	kΩ
C_{L1} C_{L2}	Recommended load capacitance versus equivalent serial resistance of the crystal or ceramic resonator (R_S)(1)	R_S=40KΩ		12.5	15	pF
i_2	XT2 driving current	V_{DD_IO}=3.3 V or 5.0 V V_{IN}=V_{SS}	1		5	µA
$t_{SU(OSC32K)}$(2)	Startup time	V_{DD_IO} is stabilized		2.5		s

1. The oscillator selection can be optimized in terms of supply current using an high quality resonator with small R_S value. Refer to crystal/ceramic resonator manufacturer for more details
2. $t_{SU(OSC32K)}$ is the start-up time measured from the moment it is enabled (by software) to a stabilized 32 kHz oscillation is reached. This value is measured for a standard crystal resonator and it can vary significantly with the crystal/ceramic resonator manufacturer

Figure 22. Typical application with a 32.768 kHz crystal or ceramic resonator



PLL characteristics

PLL Jitter Terminology

- Self-referred single period jitter (period jitter)

  Period Jitter is defined as the difference of the maximum period (T_{max}) and minimum period (T_{min}) at the output of the PLL where T_{max} is the maximum time difference between 2 consecutive clock rising edges and T_{min} is the minimum time difference between 2 consecutive clock rising edges.

  See *Figure 23*

- Self-referred long term jitter (N period jitter)

  Self-referred long term Jitter is defined as the difference of the maximum period (T_{max}) and minimum period (T_{min}) at the output of the PLL where T_{max} is the maximum time

difference between N+1 consecutive clock rising edges and T_{min} is the minimum time difference between N+1 consecutive clock rising edges.

N should be kept sufficiently large to have a long term jitter (ex: thousands).

For N=1, this becomes the single period jitter.

See *Figure 23*

- Cycle-to-cycle jitter (N period jitter)

  This corresponds to the time variation between adjacent cycles over a random sample of adjacent clock cycles pairs. Jitter(cycle-to-cycle) = Max(Tcycle n- Tcycle n-1) for n=1 to N.

  See *Figure 24*

Figure 23. Self-referred jitter (single and long term)

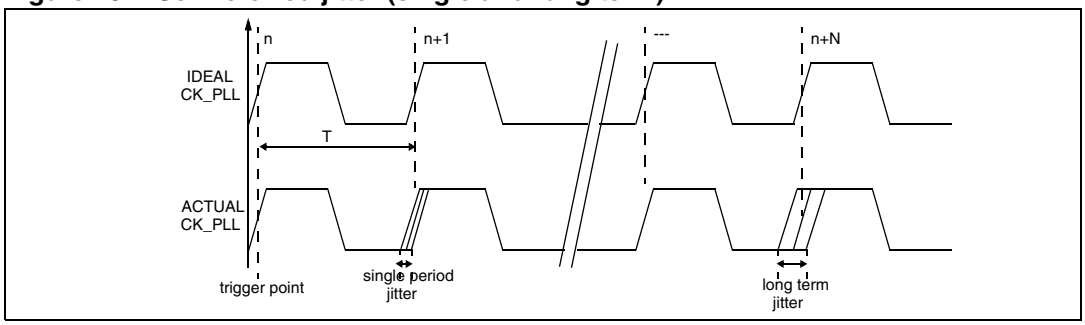
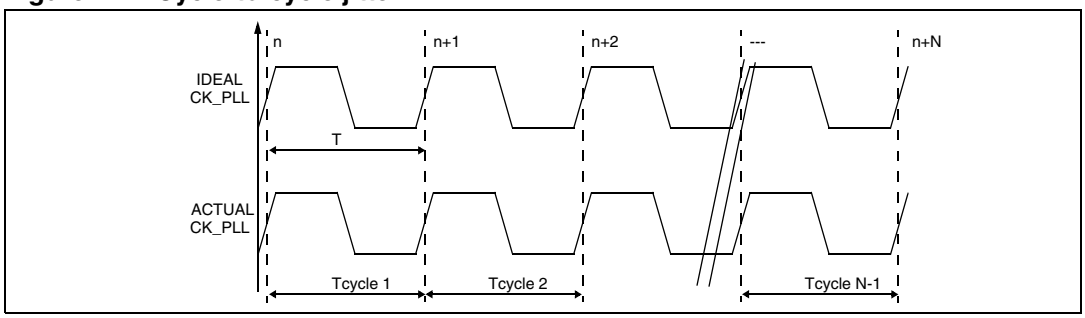


Figure 24. Cycle-to-cycle jitter



6.3.6 Memory characteristics

Flash memory

Subject to general operating conditions for V_{DD_IO} and V_{18}, T_A = -40 to 105 °C unless otherwise specified.

Table 26. Flash memory characteristics

Symbol	Parameter	Test Conditions	Value		Unit
			Typ	Max(1)	
t_{PW}	Word Program		35		µs
t_{PDW}	Double Word Program		60		µs
t_{PB0}	Bank 0 Program (256K)	Single Word programming of a checker-board pattern	2	4.9(2)	s
t_{PB1}	Bank 1 Program (16K)	Single Word programming of a checker-board pattern	125	224(2)	ms
t_{ES}	Sector Erase (64K)	Not preprogrammed (all 1) Preprogrammed (all 0)	1.54 1.176	2.94(2) 2.38(2)	s
t_{ES}	Sector Erase (8K)	Not preprogrammed (all 1) Preprogrammed (all 0)	392 343	560(2) 532(2)	ms
t_{ES}	Bank 0 Erase (256K)	Not preprogrammed (all 1) Preprogrammed (all 0)	8.0 6.6	13.7 11.2	s
t_{ES}	Bank 1 Erase (16K)	Not preprogrammed (all 1) Preprogrammed (all 0)	0.9 0.8	1.5 1.3	s
t_{RPD}	Recovery when disabled			20	µs
t_{PSL}	Program Suspend Latency			10	µs
t_{ESL}	Erase Suspend Latency			300	µs

1. Data based on characterisation not tested in production
2. 10K program/erase cycles.

Table 27. Flash memory endurance and data retention

Symbol	Parameter	Conditions	Value			Unit
			Min(1)	Typ	Max	
N_{END_B0}	Endurance (Bank 0 sectors)		10			kcycles
N_{END_B1}	Endurance (Bank 1 sectors)		100			kcycles
Y_{RET}	Data Retention	T_A=85° C	20			Years
t_{ESR}	Erase Suspend Rate	Min time from Erase Resume to next Erase Suspend	20			ms

1. Data based on characterisation not tested in production.

6.3.7 EMC characteristics

Susceptibility tests are performed on a sample basis during product characterization.

Functional EMS (electro magnetic susceptibility)

Based on a simple running application on the product (toggling 2 LEDs through I/O ports), the product is stressed by two electro magnetic events until a failure occurs (indicated by the LEDs).

- **ESD**: Electro-Static Discharge (positive and negative) is applied on all pins of the device until a functional disturbance occurs. This test conforms with the IEC 1000-4-2 standard.
- **FTB**: A Burst of Fast Transient voltage (positive and negative) is applied to V_{DD} and V_{SS} through a 100pF capacitor, until a functional disturbance occurs. This test conforms with the IEC 1000-4-4 standard.

A device reset allows normal operations to be resumed. The test results are given in the table below based on the EMS levels and classes defined in application note AN1709.

Designing hardened software to avoid noise problems

EMC characterization and optimization are performed at component level with a typical application environment and simplified MCU software. It should be noted that good EMC performance is highly dependent on the user application and the software in particular.

Therefore it is recommended that the user applies EMC software optimization and prequalification tests in relation with the EMC level requested for his application.

Software recommendations:

The software flowchart must include the management of runaway conditions such as:

- Corrupted program counter
- Unexpected reset
- Critical Data corruption (control registers...)

Prequalification trials:

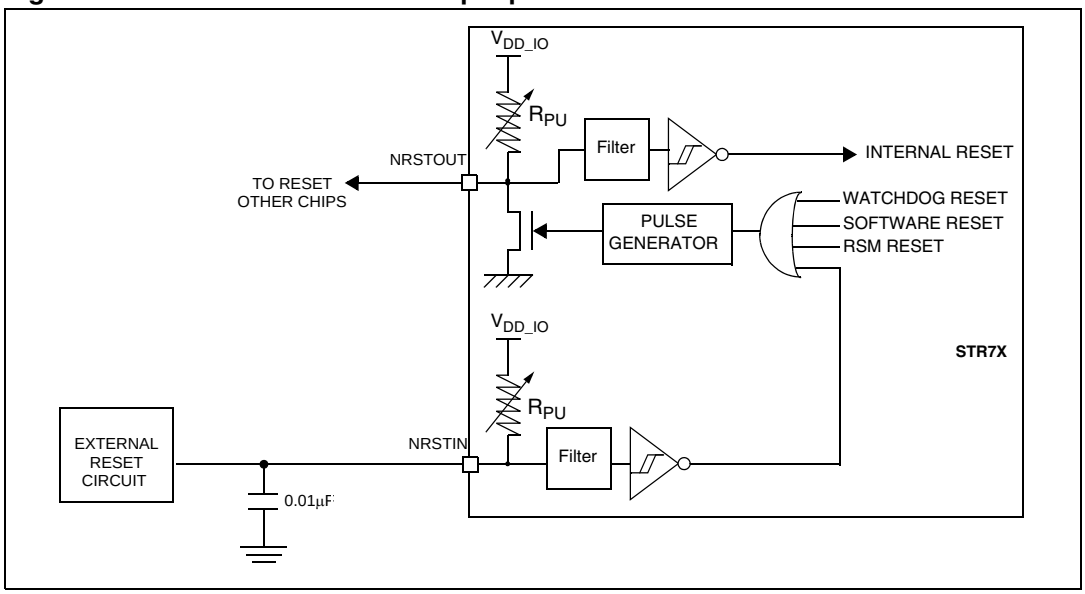
Most of the common failures (unexpected reset and program counter corruption) can be reproduced by manually forcing a low state on the RESET pin or the Oscillator pins for 1 second.

To complete these trials, ESD stress can be applied directly on the device, over the range of specification values. When unexpected behaviour is detected, the software can be hardened to prevent unrecoverable errors occurring (see application note AN1015).

Table 28. EMC characteristics

Symbol	Parameter	Conditions	Level/ Class
V_{FESD}	Voltage limits to be applied on any I/O pin to induce a functional disturbance	V_{DD_IO}=3.3 V or 5 V, T_A=+25° C, f_{CK_SYS}=32 MHz conforms to IEC 1000-4-2	Class A
V_{EFTB}	Fast transient voltage burst limits to be applied through 100pF on V_{DD} and V_{SS} pins to induce a functional disturbance	V_{DD_IO}=3.3 V or 5 V, T_A=+25° C, f_{CK_SYS}=32 MHz conforms to IEC 1000-4-4	Class A

Figure 27. Recommended NRSTIN pin protection



1. The user must ensure that the level on the NRSTIN pin can go below the $V_{IL(NRSTIN)}$ max. level specified in *NRSTIN and NRSTOUT pins on page 58*. Otherwise the reset will not be taken into account internally.

Figure 28. SPI configuration - master mode, single transfer

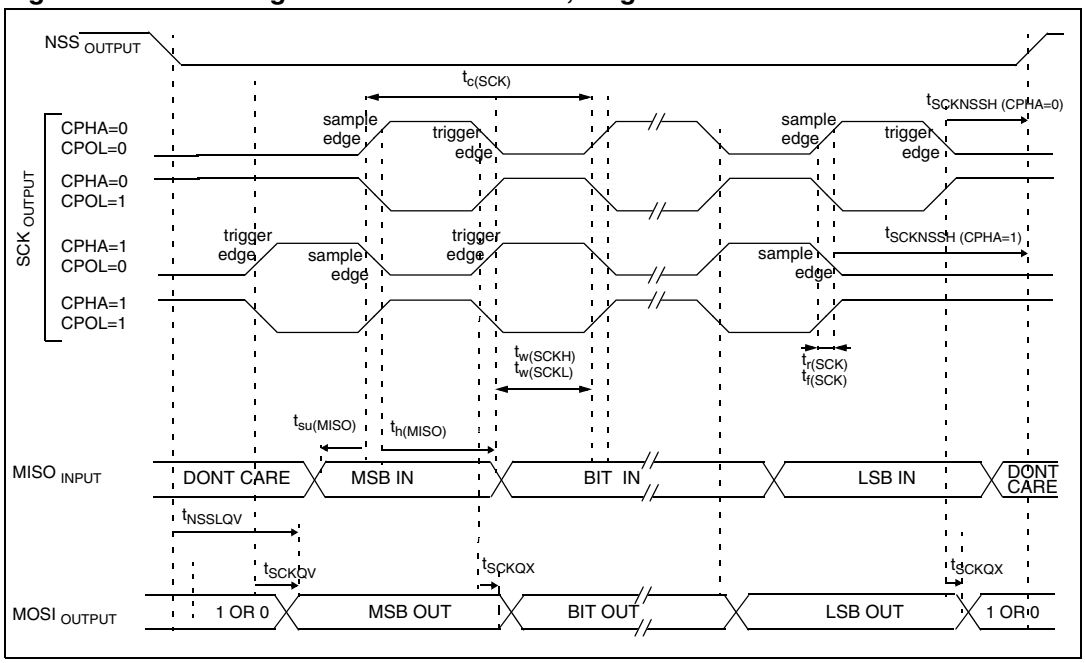


Figure 29. SPI configuration - master mode, continuous transfer, CPHA=0

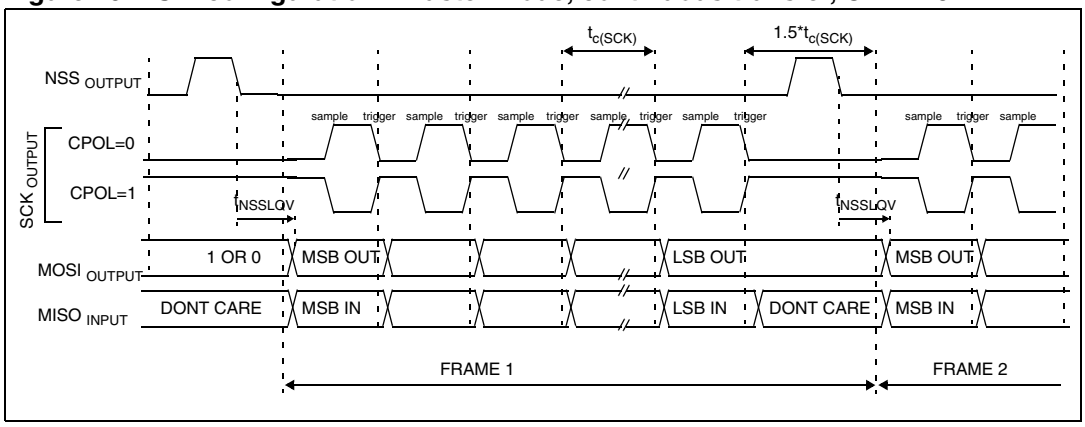
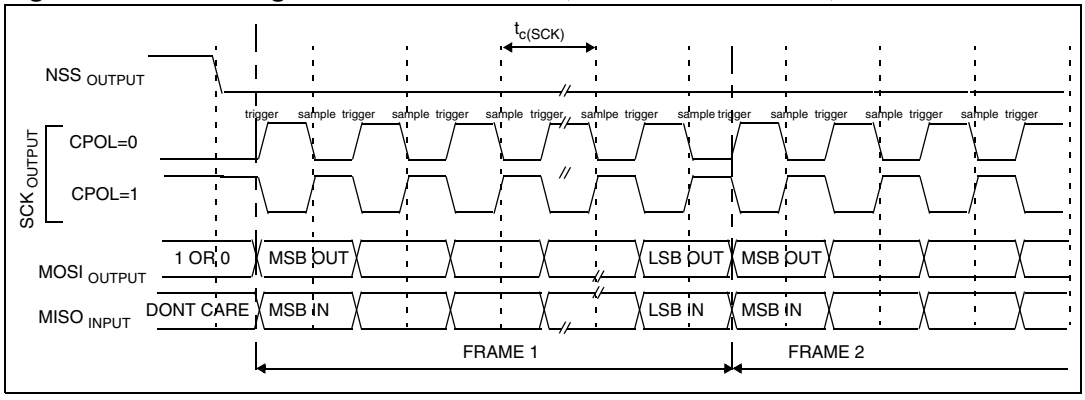


Figure 30. SPI configuration - master mode, continuous transfer, CPHA=1



SSP synchronous serial peripheral in slave mode (SPI or TI mode)

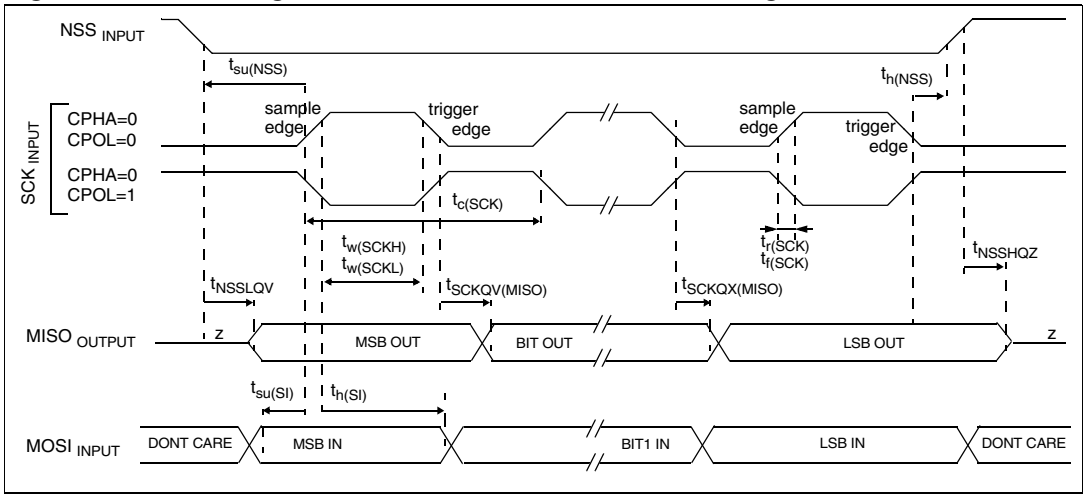
Subject to general operating conditions with $C_L \approx 45$ pF

Table 39. SSP slave mode characteristics(1)

Symbol	Parameter	Conditions		Min	Max	Unit
f_{SCK}	SPI clock frequency		SSP0		2.66 MHz (f_{PLCK}/12)	MHz
			SSP1			
$t_{su(NSS)}$	NSS input setup time w.r.t SCK first edge		SSP0	0		ns
			SSP1	0		
$t_{h(NSS)}$	NSS input hold time w.r.t SCK last edge		SSP0	t_{PCLK}+15ns		
			SSP1	t_{PCLK}+15ns		
t_{NSSLQV}	NSS low to Data Output MISO valid time		SSP0	$2t_{PCLK}$	$3t_{PCLK}$+30 ns	
			SSP1	$2t_{PCLK}$	$3t_{PCLK}$+30 ns	
t_{NSSLQZ}	NSS low to Data Output MISO invalid time		SSP0	$2t_{PCLK}$	$3t_{PCLK}$+15 ns	
			SSP1	$2t_{PCLK}$	$3t_{PCLK}$+15 ns	
t_{SCKQV}	SCK trigger edge to data output MISO valid time		SSP0		15	
			SSP1		30	
t_{SCKQX}	SCK trigger edge to data output MISO invalid time		SSP0	$2t_{PCLK}$		
			SSP1	$2t_{PCLK}$		
$t_{su(MOSI)}$	MOSI setup time w.r.t SCK sampling edge		SSP0	0		
			SSP1	0		
$t_{h(MOSI)}$	MOSI hold time w.r.t SCK sampling edge		SSP0	$3t_{PCLK}$+15 ns		
			SSP1	$3t_{PCLK}$+15 ns		

1. Data based on characterisation results, not tested in production.

Figure 33. SPI configuration, slave mode with CPHA=0, single transfer



not possible to power off the STR7x while some another I^2C master node remains powered on: otherwise, the STR7x will be powered by the protection diode.

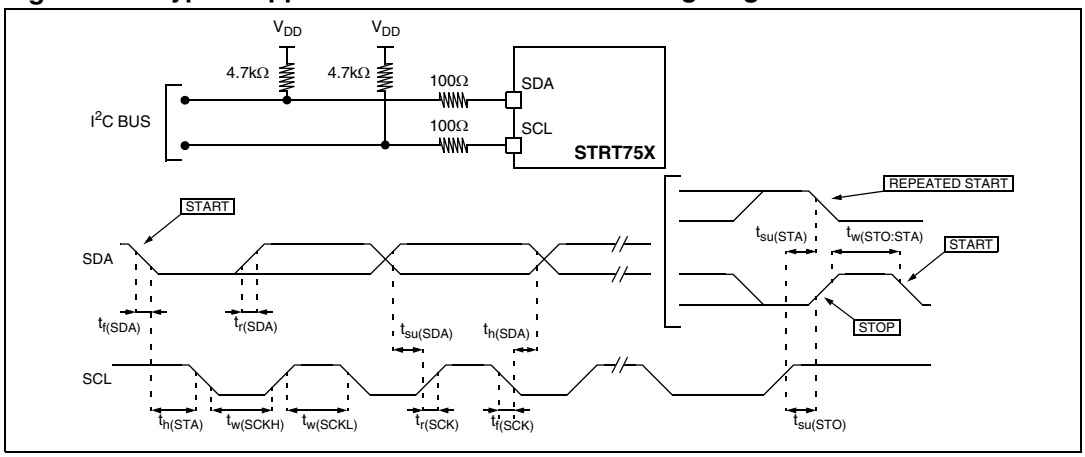
Refer to I/O port characteristics for more details on the input/output alternate function characteristics (SDA and SCL).

Table 41. SDA and SCL characteristics

Symbol	Parameter	Standard mode I^2C		Fast mode I^2C(1)		Unit
		Min(2)	Max(2)	Min(2)	Max(2)	
$t_{w(SCLL)}$	SCL clock low time	4.7		1.3		µs
$t_{w(SCLH)}$	SCL clock high time	4.0		0.6		µs
$t_{su(SDA)}$	SDA setup time	250		100		ns
$t_{h(SDA)}$	SDA data hold time	0(3)		0(4)	900(3)	ns
$t_{r(SDA)}$ $t_{r(SCL)}$	SDA and SCL rise time		1000	20+0.1C_b	300	ns
$t_{f(SDA)}$ $t_{f(SCL)}$	SDA and SCL fall time		300	20+0.1C_b	300	ns
$t_{h(STA)}$	START condition hold time	4.0		0.6		µs
$t_{su(STA)}$	Repeated START condition setup time	4.7		0.6		µs
$t_{su(STO)}$	STOP condition setup time	4.0		0.6		µs
$t_{w(STO:STA)}$	STOP to START condition time (bus free)	4.7		1.3		µs
C_b	Capacitive load for each bus line		400		400	pF

1. f_{PCLK}, must be at least 8 MHz to achieve max fast I^2C speed (400 kHz).
2. Data based on standard I^2C protocol requirement, not tested in production.
3. The maximum hold time $t_{h(SDA)}$ is not applicable
4. The device must internally provide a hold time of at least 300 ns for the SDA signal in order to bridge the undefined region of the falling edge of SCL.

Figure 40. Typical application with I^2C bus and timing diagram



1. Measurement points are done at CMOS levels: 0.3xV_{DD} and 0.7xV_{DD}.

6.3.11 USB characteristics

The USB interface is USB-IF certified (Full Speed).

Table 42. USB startup time

Symbol	Parameter	Conditions	Max	Unit
$t_{STARTUP}$	USB transceiver startup time		1	µs

Table 43. USB characteristics

USB DC Electrical Characteristics					
Symbol	**Parameter**	**Conditions**	**Min.(1)(2)**	**Max.(1)(2)**	**Unit**
Input Levels					
V_{DI}	Differential Input Sensitivity	I(DP, DM)	0.2		V
V_{CM}	Differential Common Mode Range	Includes V_{DI} range	0.8	2.5	
V_{SE}	Single Ended Receiver Threshold		1.3	2.0	
Output Levels					
V_{OL}	Static Output Level Low	R_L of 1.5 kΩ to 3.6V(3)		0.3	V
V_{OH}	Static Output Level High	R_L of 15 kΩ to V_{SS}(3)	2.8	3.6	

1. All the voltages are measured from the local ground potential.
2. It is important to be aware that the DP/DM pins are not 5 V tolerant. As a consequence, in case of a a shortcut with Vbus (typ: 5.0V), the protection diodes of the DP/DM pins will be direct biased . This will not damage the device if not more than 50 mA is sunk for longer than 24 hours but the reliability may be affected.
3. R_L is the load connected on the USB drivers

Figure 41. USB: data signal rise and fall time

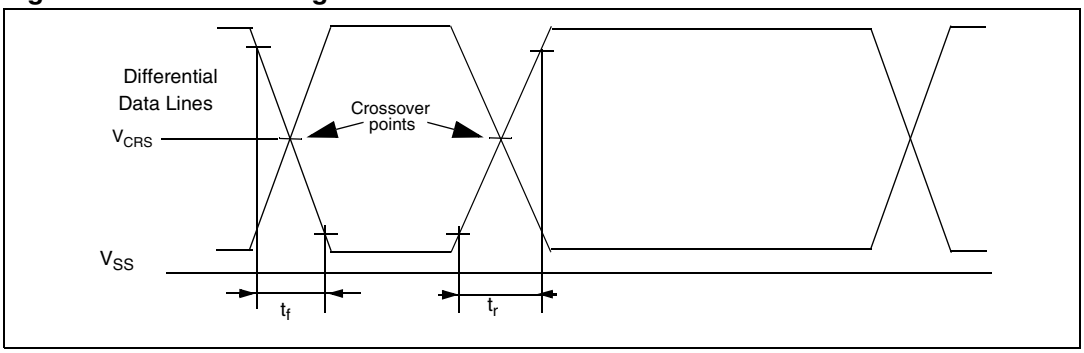


Table 44. USB: Full speed electrical characteristics

Symbol	Parameter	Conditions	Min	Max	Unit
Driver characteristics:					
t_r	Rise time(1)	C_L=50 pF	4	20	ns
t_f	Fall Time1)	C_L=50 pF	4	20	ns

Table 47. ADC accuracy

ADC accuracy with f_{CK_SYS} = 20 MHz, f_{ADC}=8 MHz, R_{AIN} < 10 kΩ This assumes that the ADC is calibrated(1)					
Symbol	**Parameter**	**Conditions**	**Typ**	**Max**	**Unit**
$\|E_T\|$	Total unadjusted error (2) (3)	V_{DDA_ADC}=3.3 V	1	1.2	LSB
		V_{DDA_ADC}=5.0 V	1	1.2	
$\|E_O\|$	Offset error(2) (3)	V_{DDA_ADC}=3.3 V	0.15	0.5	
		V_{DDA_ADC}=5.0 V	0.15	0.5	
E_G	Gain Error (2) (3)	V_{DDA_ADC}=3.3 V	-0.8	-0.2	
		V_{DDA_ADC}=5.0 V	-0.8	-0.2	
$\|E_D\|$	Differential linearity error(2) (3)	V_{DDA_ADC}=3.3 V	0.7	0.9	
		V_{DDA_ADC}=5.0 V	0.7	0.9	
$\|E_L\|$	Integral linearity error (2) (3)	V_{DDA_ADC}=3.3 V	0.6	0.8	
		V_{DDA_ADC}=5.0 V	0.6	0.8	

1. Calibration is needed once after each power-up.
2. Refer to *ADC accuracy vs. negative injection current on page 73*
3. ADC Accuracy vs. MCO (Main Clock Output): the ADC accuracy can be significantly degraded when activating the MCO on pin P0.01 while converting an analog channel (especially those which are close to the MCO pin). To avoid this, when an ADC conversion is launched, it is strongly recommended to disable the MCO.

Figure 44. ADC accuracy characteristics

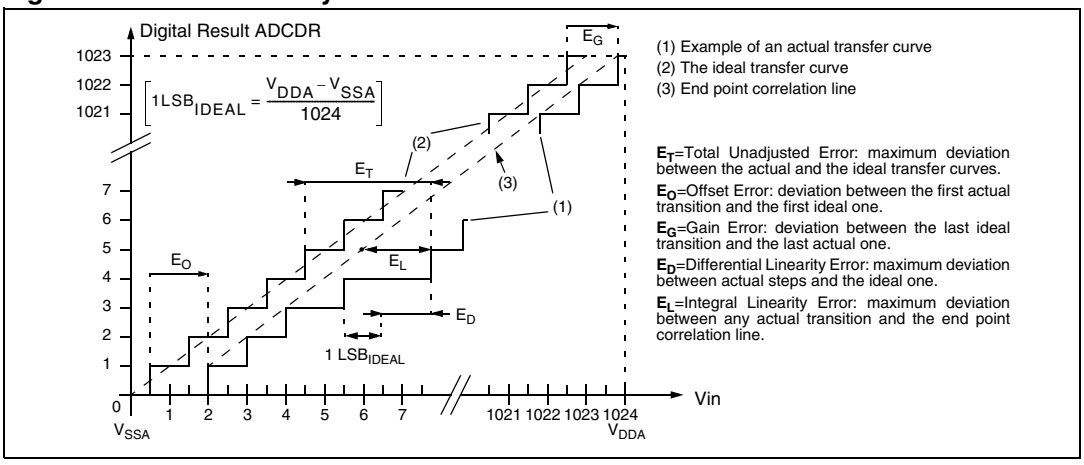
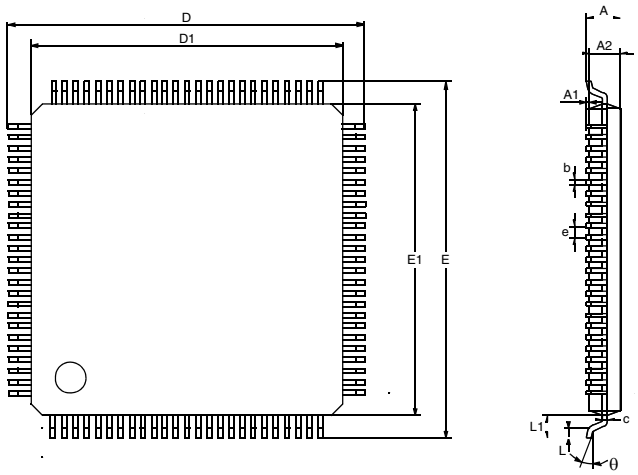


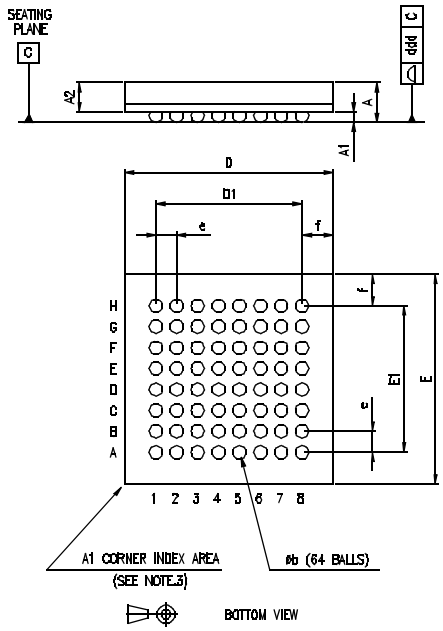
Figure 46. 100-pin low profile flat package (14x14)



Dim.	mm			inches(1)		
	Min	Typ	Max	Min	Typ	Max
A			1.60			0.0630
A1	0.05		0.15	0.0020		0.0059
A2	1.35	1.40	1.45	0.0531	0.0551	0.0571
b	0.17	0.22	0.27	0.0067	0.0087	0.0106
C	0.09		0.20	0.0035		0.0079
D		16.00			0.6299	
D1		14.00			0.5512	
E		16.00			0.6299	
E1		14.00			0.5512	
e		0.50			0.0197	
θ	0°	3.5°	7°	0°	3.5°	7°
L	0.45	0.60	0.75	0.0177	0.0236	0.0295
L1		1.00			0.0394	
	Number of Pins					
N	100					

1. Values in inches are converted from mm and rounded to 4 decimal digits.

Figure 47. 64-ball low profile fine pitch ball grid array package



Dim.	mm			inches(1)		
	Min	Typ	Max	Min	Typ	Max
A	1.210		1.700	0.0476		0.0669
A1	0.270			0.0106		
A2		1.120			0.0441	
b	0.450	0.500	0.550	0.0177	0.0197	0.0217
D	7.750	8.000	8.150	0.3051	0.3150	0.3209
D1		5.600			0.2205	
E	7.750	8.000	8.150	0.3051	0.3150	0.3209
E1		5.600			0.2205	
e	0.720	0.800	0.880	0.0283	0.0315	0.0346
f	1.050	1.200	1.350	0.0413	0.0472	0.0531
ddd			0.120			0.0047
	Number of Pins					
N	64					

1. Values in inches are converted from mm and rounded to 4 decimal digits.